Lattice Semiconductor Corporation - LFECP10E-4FN256C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10200
Total RAM Bits	282624
Number of I/O	195
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfecp10e-4fn256c

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SPR16x2	ROM16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Ripple Mode includes an optional configuration that performs arithmetic using fast carry chain methods. In this configuration (also referred to as CCU2 mode) two additional signals, Carry Generate and Carry Propagate, are generated on a per slice basis to allow fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-5 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information about using RAM in LatticeECP/EC devices, please see the list of technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Routing

There are many resources provided in the LatticeECP/EC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal and vertical directions. The x2 and x6 resources are buffered, the routing of both short and long connections between PFUs.

The ispLEVER design tool suite takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

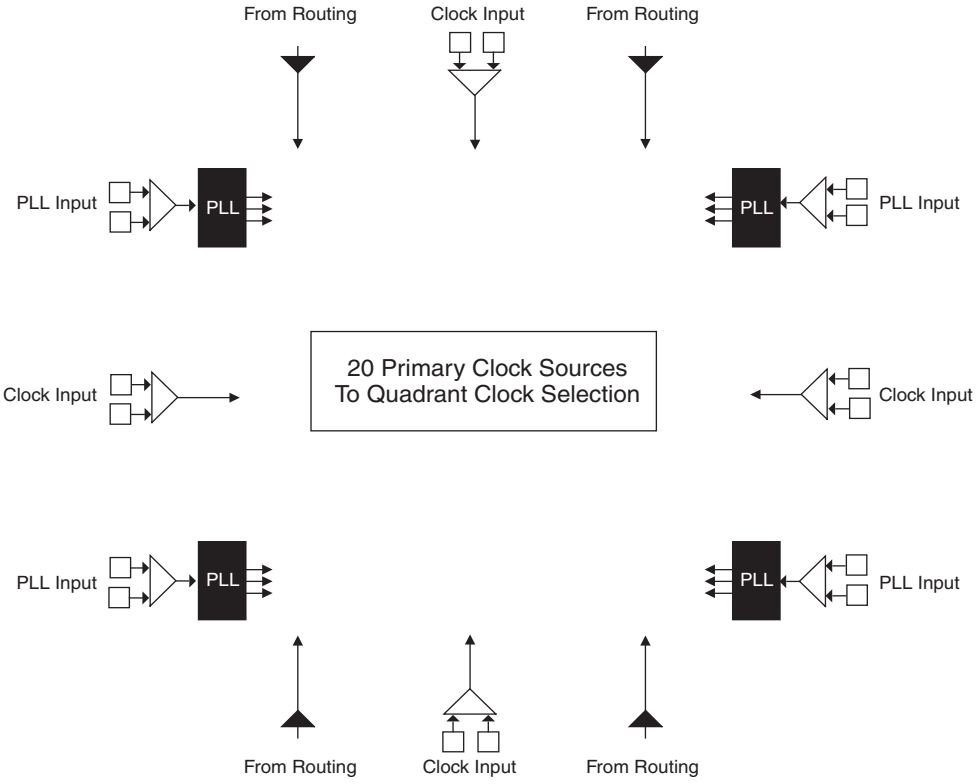
Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeECP/EC devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeECP/EC devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-6 shows the 20 primary clock sources.

Figure 2-6. Primary Clock Sources



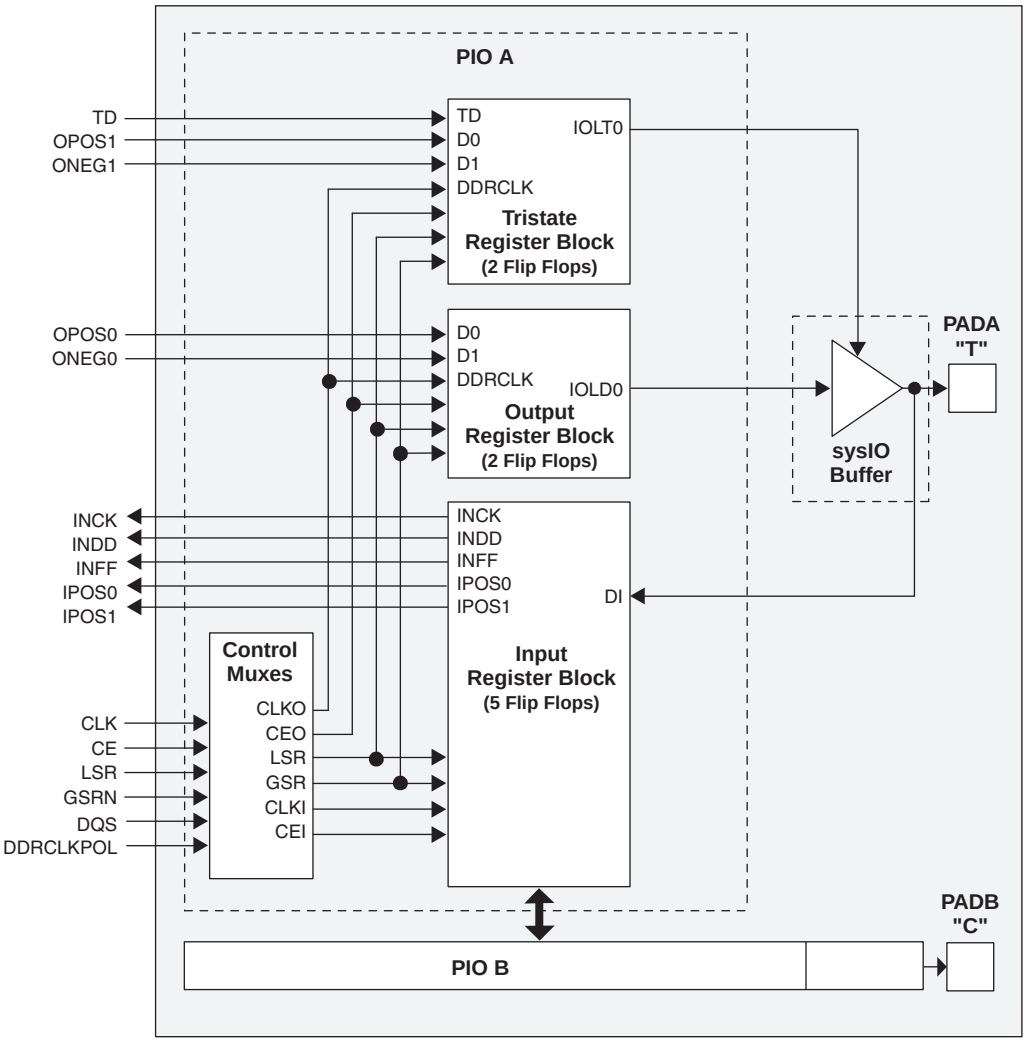
Note: Smaller devices have two PLLs.

For further information about the sysDSP block, please see the list of technical information at the end of this data sheet.

Programmable I/O Cells (PIC)

Each PIC contains two PIOs connected to their respective sysI/O Buffers which are then connected to the PADs as shown in Figure 2-24. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to sysI/O buffer, and receives input from the buffer.

Figure 2-24. PIC Diagram



Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”) as shown in Figure 2-25. The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 16 PIOs contains a delay element to facilitate the generation of DQS signals. The DQS signal feeds the DQS bus which spans the set of 16 PIOs. Figure 2-25 shows the assignment of DQS pins in each set of 16 PIOs. The exact DQS pins are shown in a dual function in the Logic Signal Connections table at the end of this data sheet. Additional detail is provided in the Signal Descriptions table at the end of this data sheet. The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP/EC devices contain two possible ports that can be used for device configuration. The test access port (TAP), which supports bit-wide configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The TAP supports both the IEEE Std. 1149.1 Boundary Scan specification and the IEEE Std. 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six of the I/Os used as dedicated pins and the rest being dual-use pins (please refer to TN1053 for more information about using the dual-use pins as general purpose I/O). There are four configuration options for LatticeECP/EC devices:

1. Industry standard SPI memories.
2. Industry standard byte wide flash and ispMACH 4000 for control/addressing.
3. Configuration from system microprocessor via the configuration bus or TAP.
4. Industry standard FPGA board memory.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port. Once a configuration port is selected, that port is locked and another configuration port cannot be activated until the next power-up sequence.

For more information about device configuration, please see the list of technical documentation at the end of this data sheet.

Internal Logic Analyzer Capability (ispTRACY)

All LatticeECP/EC devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information about ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

External Resistor

LatticeECP/EC devices require a single external, 10K ohm +/- 1% value between the XRES pin and ground. Device configuration will not be completed if this resistor is missing. There is no boundary scan register on the external resistor pad.

Typical Building Block Function Performance

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	5.5	ns
32-bit decoder	6.9	ns
64-bit decoder	7.1	ns
4:1 MUX	4.3	ns
8:1 MUX	4.7	ns
16:1 MUX	5.0	ns
32:1 MUX	5.5	ns

Register-to-Register Performance[1]

Function	-5 Timing	Units
Basic Functions		
16 bit decoder	410	MHz
32 bit decoder	283	MHz
64 bit decoder	272	MHz
4:1 MUX	613	MHz
8:1 MUX	565	MHz
16:1 MUX	526	MHz
32:1 MUX	442	MHz
8-bit adder	363	MHz
16-bit adder	353	MHz
64-bit adder	196	MHz
16-bit counter	414	MHz
32-bit counter	317	MHz
64-bit counter	216	MHz
64-bit accumulator	178	MHz
Embedded Memory Functions		
256x36 Single Port RAM	280	MHz
512x18 True-Dual Port RAM	280	MHz
Distributed Memory Functions		
16x2 Single Port RAM	460	MHz
64x2 Single Port RAM	375	MHz
128x4 Single Port RAM	294	MHz
32x2 Pseudo-Dual Port RAM	392	MHz
64x4 Pseudo-Dual Port RAM	332	MHz
DSP Function[2]		
9x9 Pipelined Multiply/Accumulate	242	MHz
18x18 Pipelined Multiply/Accumulate	238	MHz
36x36 Pipelined Multiply	235	MHz

1. These timing numbers were generated using the ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.
2. Applies to LatticeECP devices only.

Timing v.G 0.30

LatticeECP/EC External Switching Characteristics (Continued)

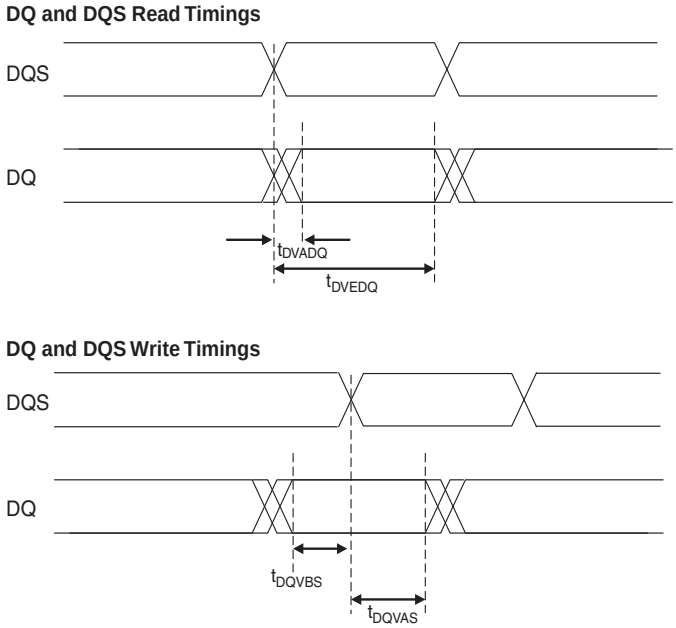
Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	200	95	166	95	133	MHz
Primary and Secondary Clock[6]									
f_{MAX_PRI}[2]	Frequency for Primary Clock Tree	All	—	420	—	378	—	340	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	All	—	250	—	300	—	350	ps

1. General timing numbers based on LVCMOS2.5V, 12 mA. Loading of 0 pF.
2. Using LVDS I/O standard.
3. DDR timing numbers based on SSTL I/O.
4. DDR specifications are characterized but not tested.
5. UI is average bit period.
6. Based on a single primary clock.
7. These timing numbers were generated using ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Timing v.G 0.30

Figure 3-5. DDR Timings



LatticeECP/EC Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.18	—	0.21	—	0.25	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.14	—	-0.17	—	-0.20	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.47	—	1.76	—	2.05	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns
DSP Block Timing[2, 3]								
t_{SUI_DSP}	Input Register Setup Time	-0.38	—	-0.30	—	-0.23	—	ns
t_{HI_DSP}	Input Register Hold Time	0.71	—	0.86	—	1.00	—	ns
t_{SUP_DSP}	Pipeline Register Setup Time	3.31	—	3.98	—	4.64	—	ns
t_{HP_DSP}	Pipeline Register Hold Time	0.71	—	0.86	—	1.00	—	ns
t_{SUO_DSP}[4]	Output Register Setup Time	5.54	—	6.64	—	7.75	—	ns
t_{HO_DSP}[4]	Output Register Hold Time	0.71	—	0.86	—	1.00	—	ns
t_{COI_DSP}[4]	Input Register Clock to Output Time	—	7.50	—	9.00	—	10.50	ns
t_{COP_DSP}[4]	Pipeline Register Clock to Output Time	—	4.66	—	5.60	—	6.53	ns
t_{COO_DSP}	Output Register Clock to Output Time	—	1.47	—	1.77	—	2.06	ns
$t_{SUADSUB}$	AdSub Input Register Setup Time	-0.38	—	-0.30	—	-0.23	—	ns
t_{HADSUB}	AdSub Input Register Hold Time	0.71	—	0.86	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.
2. These parameters apply to LatticeECP devices only.
3. DSP Block is configured in Multiply Add/Sub 18 x 18 Mode.
4. These parameters include the Adder Subtractor block in the path.

Timing v.G 0.30

Timing Diagrams

PFU Timing Diagrams

Figure 3-6. Slice Single/Dual Port Write Cycle Timing

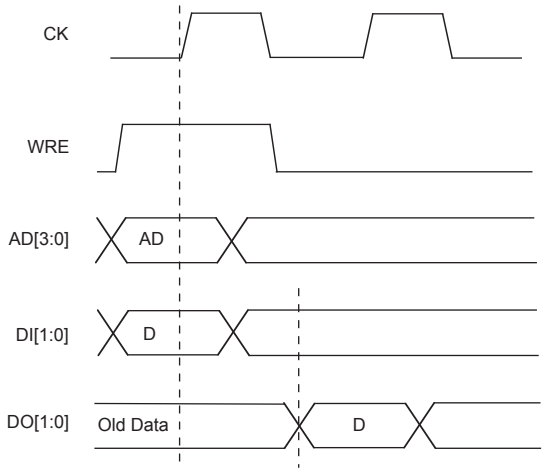


Figure 3-7. Slice Single /Dual Port Read Cycle Timing

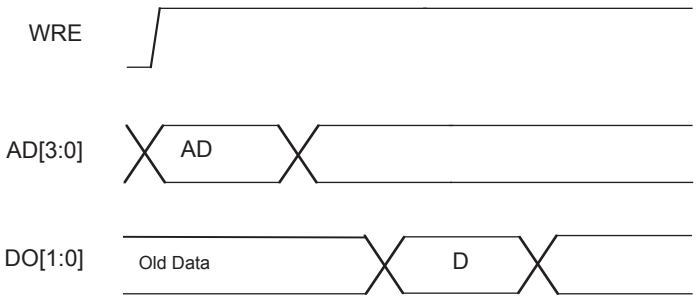


Figure 3-14. sysCONFIG Master Serial Port Timing

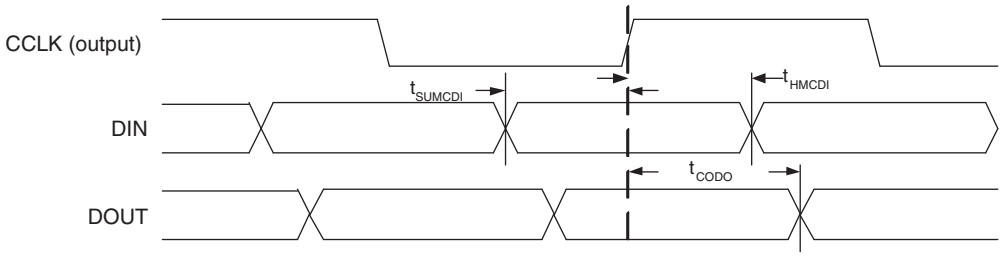


Figure 3-15. sysCONFIG Slave Serial Port Timing

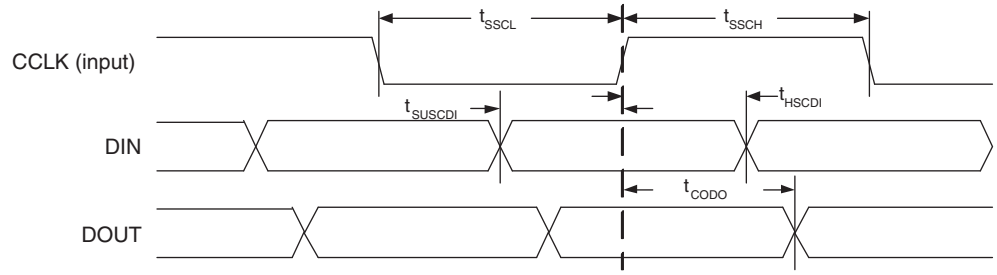
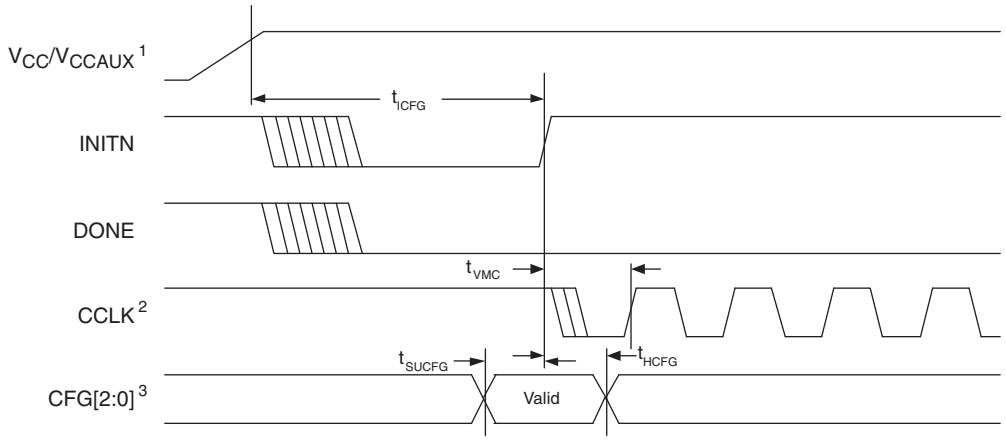


Figure 3-16. Power-On-Reset (POR) Timing



1. Time taken from V_{CC} or V_{CCAUX}, whichever is the last to reach its V_{MIN}.
2. Device is in a Master Mode.
3. The CFG pins are normally static (hard wired).

LFEC1, LFEC3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
82	PT11B	1	C	VREF2_1	PT19B	1	C	VREF2_1
83	PT11A	1	T	VREF1_1	PT19A	1	T	VREF1_1
84	PT10B	1	C		PT18B	1	C	
85	PT10A	1	T		PT18A	1	T	
86	VCCIO1	1			VCCIO1	1		
87	VCCAUX	-			VCCAUX	-		
88	PT9B	0	C	PCLKC0_0	PT17B	0	C	PCLKC0_0
89	GND0	0			GND0	0		
90	PT9A	0	T	PCLKT0_0	PT17A	0	T	PCLKT0_0
91	PT8B	0	C	VREF1_0	PT16B	0	C	VREF1_0
92	PT8A	0	T	VREF2_0	PT16A	0	T	VREF2_0
93	PT7B	0			PT15B	0		
94	PT6B	0	C		PT14B	0	C	
95	PT6A	0	T	TDQS6	PT14A	0	T	TDQS14
96	PT4B	0	C		PT12B	0	C	
97	PT4A	0	T		PT12A	0	T	
98	PT2B	0	C		PT10B	0	C	
99	PT2A	0	T		PT10A	0	T	
100	VCCIO0	0			VCCIO0	0		

*Double bonded to the pin.

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
1*	GND0 GND7	-			GND0 GND7	-		
2	VCCIO7	7			VCCIO7	7		
3	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
4	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
5	NC	-			NC	-		
6	NC	-			NC	-		
7	NC	-			PL3B	7		
8	NC	-			PL4A	7	T	
9	NC	-			PL4B	7	C	
10	NC	-			PL5A	7	T	
11	NC	-			PL5B	7	C	
12	NC	-			PL6A	7	T	LDQS6
13	NC	-			VCCIO7	7		
14	NC	-			PL6B	7	C	
15	PL3A	7	T		PL7A	7	T	
16	PL3B	7	C		PL7B	7	C	
17	PL4A	7	T		PL8A	7	T	
18	NC	-			NC	-		
19	PL4B	7	C		PL8B	7	C	
20	PL5A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
21	PL5B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
22	NC	-			VCCAUX	-		
23	XRES	6			XRES	6		
24	NC	-			NC	-		
25	NC	-			NC	-		
26	VCC	-			VCC	-		
27	TCK	6			TCK	6		
28	GND	-			GND	-		
29	TDI	6			TDI	6		
30	TMS	6			TMS	6		
31	TDO	6			TDO	6		
32	VCCJ	6			VCCJ	6		
33	PL7A	6	T	LLM0_PLLT_IN_A	PL11A	6	T	LLM0_PLLT_IN_A
34	PL7B	6	C	LLM0_PLLC_IN_A	PL11B	6	C	LLM0_PLLC_IN_A
35	PL8A	6	T	LLM0_PLLT_FB_A	PL12A	6	T	LLM0_PLLT_FB_A
36	PL8B	6	C	LLM0_PLLC_FB_A	PL12B	6	C	LLM0_PLLC_FB_A
37	VCCIO6	6			VCCIO6	6		
38	PL9A	6	T		PL13A	6	T	
39	PL9B	6	C		PL13B	6	C	
40	PL10A	6	T		PL14A	6	T	
41	GND6	6			GND6	6		
42	PL10B	6	C		PL14B	6	C	

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
169	PT13A	1	T		PT21A	1	T	
170	PT12B	1	C		PT20B	1	C	
171	PT12A	1	T		PT20A	1	T	
172	PT11B	1	C	VREF2_1	PT19B	1	C	VREF2_1
173	PT11A	1	T	VREF1_1	PT19A	1	T	VREF1_1
174	PT10B	1	C		PT18B	1	C	
175	PT10A	1	T		PT18A	1	T	
176	VCCIO1	1			VCCIO1	1		
177	VCCAUX	-			VCCAUX	-		
178	PT9B	0	C	PCLKC0_0	PT17B	0	C	PCLKC0_0
179	GND0	0			GND0	0		
180	PT9A	0	T	PCLKT0_0	PT17A	0	T	PCLKT0_0
181	PT8B	0	C	VREF1_0	PT16B	0	C	VREF1_0
182	PT8A	0	T	VREF2_0	PT16A	0	T	VREF2_0
183	PT7B	0	C		PT15B	0	C	
184	PT7A	0	T		PT15A	0	T	
185	PT6B	0	C		PT14B	0	C	
186	PT6A	0	T	TDQS6	PT14A	0	T	TDQS14
187	VCCIO0	0			VCCIO0	0		
188	PT5B	0	C		PT13B	0	C	
189	NC	-			GND0	0		
190	PT5A	0	T		PT13A	0	T	
191	PT4B	0	C		PT12B	0	C	
192	PT4A	0	T		PT12A	0	T	
193	PT3B	0	C		PT11B	0	C	
194	PT3A	0	T		PT11A	0	T	
195	PT2B	0	C		PT10B	0	C	
196	PT2A	0	T		PT10A	0	T	
197	NC	-			VCCIO0	0		
198	NC	-			PT6B	0	C	
199	NC	-			PT6A	0	T	TDQS6
200	NC	-			PT5B	0	C	
201	NC	-			PT5A	0	T	
202	NC	-			PT4B	0	C	
203	NC	-			PT4A	0	T	
204	NC	-			PT3B	0	C	
205	NC	-			PT3A	0	T	
206	NC	-			PT2B	0	C	
207	NC	-			PT2A	0	T	
208	VCCIO0	0			VCCIO0	0		

* Double bonded to the pin.

LFECP/EC6, LFECP/EC10 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFECP6/LFEC6				LFECP10/LFEC10			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
169	PT21A	1	T		PT29A	1	T	
170	PT20B	1	C		PT28B	1	C	
171	PT20A	1	T		PT28A	1	T	
172	PT19B	1	C	VREF2_1	PT27B	1	C	VREF2_1
173	PT19A	1	T	VREF1_1	PT27A	1	T	VREF1_1
174	PT18B	1	C		PT26B	1	C	
175	PT18A	1	T		PT26A	1	T	
176	VCCIO1	1			VCCIO1	1		
177	VCCAUX	-			VCCAUX	-		
178	PT17B	0	C	PCLKC0_0	PT25B	0	C	PCLKC0_0
179	GND0	0			GND0	0		
180	PT17A	0	T	PCLKT0_0	PT25A	0	T	PCLKT0_0
181	PT16B	0	C	VREF1_0	PT24B	0	C	VREF1_0
182	PT16A	0	T	VREF2_0	PT24A	0	T	VREF2_0
183	PT15B	0	C		PT23B	0	C	
184	PT15A	0	T		PT23A	0	T	
185	PT14B	0	C		PT22B	0	C	
186	PT14A	0	T	TDQS14	PT22A	0	T	TDQS22
187	VCCIO0	0			VCCIO0	0		
188	PT13B	0	C		PT21B	0	C	
189	GND0	0			GND0	0		
190	PT13A	0	T		PT21A	0	T	
191	PT12B	0	C		PT20B	0	C	
192	PT12A	0	T		PT20A	0	T	
193	PT11B	0	C		PT19B	0	C	
194	PT11A	0	T		PT19A	0	T	
195	PT10B	0	C		PT18B	0	C	
196	PT10A	0	T		PT18A	0	T	
197	VCCIO0	0			VCCIO0	0		
198	PT6B	0	C		PT6B	0	C	
199	PT6A	0	T	TDQS6	PT6A	0	T	TDQS6
200	PT5B	0	C		PT5B	0	C	
201	PT5A	0	T		PT5A	0	T	
202	PT4B	0	C		PT4B	0	C	
203	PT4A	0	T		PT4A	0	T	
204	PT3B	0	C		PT3B	0	C	
205	PT3A	0	T		PT3A	0	T	
206	PT2B	0	C		PT2B	0	C	
207	PT2A	0	T		PT2A	0	T	
208	VCCIO0	0			VCCIO0	0		

*Double bonded to the pin.

LFECP/EC10 and LFECP/EC15 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFECP10/LFEC10				LFECP15/LFEC15			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
P14	PR35B	3	C		PR43B	3	C	
P15	PR35A	3	T		PR43A	3	T	
R15	PR34B	3	C		PR42B	3	C	
R16	PR34A	3	T		PR42A	3	T	
M13	PR33B	3	C		PR41B	3	C	
M14	PR33A	3	T	RDQS33	PR41A	3	T	RDQS41
P16	PR32B	3	C	RLM0_PLLC_FB_A	PR40B	3	C	RLM0_PLLC_FB_A
GND	GND3	3			GND3	3		
N16	PR32A	3	T	RLM0_PLLT_FB_A	PR40A	3	T	RLM0_PLLT_FB_A
N15	PR31B	3	C	RLM0_PLLC_IN_A	PR39B	3	C	RLM0_PLLC_IN_A
M15	PR31A	3	T	RLM0_PLLT_IN_A	PR39A	3	T	RLM0_PLLT_IN_A
M16	PR30B	3	C	DI/CSSPIN	PR38B	3	C	DI/CSSPIN
L16	PR30A	3	T	DOUT/CSON	PR38A	3	T	DOUT/CSON
K16	PR29B	3	C	BUSY/SISPI	PR37B	3	C	BUSY/SISPI
J16	PR29A	3	T	D7/SPID0	PR37A	3	T	D7/SPID0
L12	CFG2	3			CFG2	3		
L14	CFG1	3			CFG1	3		
L13	CFG0	3			CFG0	3		
K13	PROGRAMN	3			PROGRAMN	3		
L15	CCLK	3			CCLK	3		
K15	INITN	3			INITN	3		
K14	DONE	3			DONE	3		
GND	GND3	3			GND3	3		
H16	PR27B	3	C		PR31B	3	C	
-	-	-			GND3	3		
H15	PR27A	3	T		PR31A	3	T	
G16	PR26B	3	C		PR30B	3	C	
G15	PR26A	3	T		PR30A	3	T	
K12	PR25B	3	C		PR29B	3	C	
J12	PR25A	3	T		PR29A	3	T	
J14	PR24B	3	C		PR28B	3	C	
J15	PR24A	3	T	RDQS24	PR28A	3	T	RDQS28
F16	PR23B	3	C		PR27B	3	C	
GND	GND3	3			GND3	3		
F15	PR23A	3	T		PR27A	3	T	
J13	PR22B	3	C		PR26B	3	C	
H13	PR22A	3	T		PR26A	3	T	
H14	PR21B	3	C		PR25B	3	C	
G14	PR21A	3	T		PR25A	3	T	
E16	PR20B	3	C		PR24B	3	C	
E15	PR20A	3	T		PR24A	3	T	
H12	PR18B	2	C	PCLKC2_0	PR22B	2	C	PCLKC2_0
GND	GND2	2			GND2	2		

LFECP/EC10 and LFECP/EC15 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFECP10/LFEC10				LFECP15/LFEC15			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
A10	PT25B	0	C	PCLKC0_0	PT25B	0	C	PCLKC0_0
GND	GND0	0			GND0	0		
B10	PT25A	0	T	PCLKT0_0	PT25A	0	T	PCLKT0_0
C9	PT24B	0	C	VREF1_0	PT24B	0	C	VREF1_0
B9	PT24A	0	T	VREF2_0	PT24A	0	T	VREF2_0
E9	PT23B	0	C		PT23B	0	C	
D9	PT23A	0	T		PT23A	0	T	
D8	PT22B	0	C		PT22B	0	C	
C8	PT22A	0	T	TDQS22	PT22A	0	T	TDQS22
A9	PT21B	0	C		PT21B	0	C	
GND	GND0	0			GND0	0		
A8	PT21A	0	T		PT21A	0	T	
B8	PT20B	0	C		PT20B	0	C	
B7	PT20A	0	T		PT20A	0	T	
D7	PT19B	0	C		PT19B	0	C	
C7	PT19A	0	T		PT19A	0	T	
A7	PT18B	0	C		PT18B	0	C	
A6	PT18A	0	T		PT18A	0	T	
E7	PT17B	0	C		PT17B	0	C	
GND	GND0	0			GND0	0		
E6	PT17A	0	T		PT17A	0	T	
D6	PT16B	0	C		PT16B	0	C	
C6	PT16A	0	T		PT16A	0	T	
B6	PT15B	0	C		PT15B	0	C	
B5	PT15A	0	T		PT15A	0	T	
A5	PT14B	0	C		PT14B	0	C	
A4	PT14A	0	T	TDQS14	PT14A	0	T	TDQS14
A3	PT13B	0	C		PT13B	0	C	
-	GND0	0			GND0	0		
A2	PT13A	0	T		PT13A	0	T	
B2	PT12B	0	C		PT12B	0	C	
B3	PT12A	0	T		PT12A	0	T	
D5	PT11B	0	C		PT11B	0	C	
C5	PT11A	0	T		PT11A	0	T	
C4	PT10B	0	C		PT10B	0	C	
B4	PT10A	0	T		PT10A	0	T	
GND	GND0	0			GND0	0		
GND	GND0	0			GND0	0		
A1	GND	-			GND	-		
A16	GND	-			GND	-		
G10	GND	-			GND	-		
G7	GND	-			GND	-		
G8	GND	-			GND	-		

LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
A4	NC	-			A4	PT9B	0	C		A4	PT9B	0	C	
B4	NC	-			B4	PT9A	0	T		B4	PT9A	0	T	
C4	NC	-			C4	PT8B	0	C		C4	PT8B	0	C	
C5	NC	-			C5	PT8A	0	T		C5	PT8A	0	T	
D6	NC	-			D6	PT7B	0	C		D6	PT7B	0	C	
B5	NC	-			B5	PT7A	0	T		B5	PT7A	0	T	
E6	NC	-			E6	PT6B	0	C		E6	PT6B	0	C	
C6	NC	-			C6	PT6A	0	T	TDQS6	C6	PT6A	0	T	TDQS6
A3	NC	-			A3	PT5B	0	C		A3	PT5B	0	C	
B3	NC	-			B3	PT5A	0	T		B3	PT5A	0	T	
F6	NC	-			F6	PT4B	0	C		F6	PT4B	0	C	
D5	NC	-			D5	PT4A	0	T		D5	PT4A	0	T	
F7	NC	-			F7	PT3B	0	C		F7	PT3B	0	C	
E8	NC	-			E8	PT3A	0	T		E8	PT3A	0	T	
G6	NC	-			G6	PT2B	0	C		G6	PT2B	0	C	
E7	NC	-			E7	PT2A	0	T		E7	PT2A	0	T	
GND	-	-			GND	GND0	0			GND	GND0	0		
A1	GND	-			A1	GND	-			A1	GND	-		
A22	GND	-			A22	GND	-			A22	GND	-		
AB1	GND	-			AB1	GND	-			AB1	GND	-		
AB22	GND	-			AB22	GND	-			AB22	GND	-		
H15	GND	-			H15	GND	-			H15	GND	-		
H8	GND	-			H8	GND	-			H8	GND	-		
J10	GND	-			J10	GND	-			J10	GND	-		
J11	GND	-			J11	GND	-			J11	GND	-		
J12	GND	-			J12	GND	-			J12	GND	-		
J13	GND	-			J13	GND	-			J13	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
J9	GND	-			J9	GND	-			J9	GND	-		
K10	GND	-			K10	GND	-			K10	GND	-		
K11	GND	-			K11	GND	-			K11	GND	-		
K12	GND	-			K12	GND	-			K12	GND	-		
K13	GND	-			K13	GND	-			K13	GND	-		
K14	GND	-			K14	GND	-			K14	GND	-		
K9	GND	-			K9	GND	-			K9	GND	-		
L10	GND	-			L10	GND	-			L10	GND	-		
L11	GND	-			L11	GND	-			L11	GND	-		
L12	GND	-			L12	GND	-			L12	GND	-		
L13	GND	-			L13	GND	-			L13	GND	-		
L14	GND	-			L14	GND	-			L14	GND	-		
L9	GND	-			L9	GND	-			L9	GND	-		
M10	GND	-			M10	GND	-			M10	GND	-		
M11	GND	-			M11	GND	-			M11	GND	-		
M12	GND	-			M12	GND	-			M12	GND	-		
M13	GND	-			M13	GND	-			M13	GND	-		
M14	GND	-			M14	GND	-			M14	GND	-		
M9	GND	-			M9	GND	-			M9	GND	-		
N10	GND	-			N10	GND	-			N10	GND	-		
N11	GND	-			N11	GND	-			N11	GND	-		
N12	GND	-			N12	GND	-			N12	GND	-		

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
N22	PR30A	3	T		N22	PR42A	3	T	
N19	PR29B	3	C		N19	PR41B	3	C	
N18	PR29A	3	T		N18	PR41A	3	T	
M21	PR28B	3	C		M21	PR40B	3	C	
L20	PR28A	3	T	RDQS28	L20	PR40A	3	T	RDQS40
L21	PR27B	3	C		L21	PR39B	3	C	
GND	GND3	3			GND	GND3	3		
M20	PR27A	3	T		M20	PR39A	3	T	
M18	PR26B	3	C		M18	PR38B	3	C	
M19	PR26A	3	T		M19	PR38A	3	T	
M22	PR25B	3	C		M22	PR37B	3	C	
L22	PR25A	3	T		L22	PR37A	3	T	
K22	PR24B	3	C		K22	PR36B	3	C	
K21	PR24A	3	T		K21	PR36A	3	T	
J22	PR22B	2	C	PCLKC2_0	J22	PR34B	2	C	PCLKC2_0
GND	GND2	2			GND	GND2	2		
J21	PR22A	2	T	PCLKT2_0	J21	PR34A	2	T	PCLKT2_0
H22	PR21B	2	C		H22	PR33B	2	C	
H21	PR21A	2	T		H21	PR33A	2	T	
L19	PR20B	2	C		L19	PR32B	2	C	
L18	PR20A	2	T		L18	PR32A	2	T	
K20	PR19B	2	C		K20	PR31B	2	C	
J20	PR19A	2	T	RDQS19	J20	PR31A	2	T	RDQS31
K19	PR18B	2	C		K19	PR30B	2	C	
GND	GND2	2			GND	GND2	2		
K18	PR18A	2	T		K18	PR30A	2	T	
G22	PR17B	2	C		G22	PR29B	2	C	
F22	PR17A	2	T		F22	PR29A	2	T	
F21	PR16B	2	C		F21	PR28B	2	C	
E22	PR16A	2	T		E22	PR28A	2	T	
E21	PR15B	2	C		E21	PR27B	2	C	
D22	PR15A	2	T		D22	PR27A	2	T	
G21	PR14B	2	C		G21	PR26B	2	C	
G20	PR14A	2	T		G20	PR26A	2	T	
GND	GND2	2			GND	GND2	2		
J18	PR13B	2	C		J18	PR25B	2	C	
H19	PR13A	2	T		H19	PR25A	2	T	
J19	PR12B	2	C		J19	PR24B	2	C	
H20	PR12A	2	T		H20	PR24A	2	T	
H17	PR11B	2	C		H17	PR23B	2	C	
H18	PR11A	2	T		H18	PR23A	2	T	RDQS23
D21	PR9B	2	C	RUM0_PLLC_FB_A	D21	PR17B	2	C	RUM0_PLLC_FB_A
GND	GND2	2			GND	GND2	2		
GND	-	-			GND	GND2	2		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
M10	GND	-			M10	GND	-		
M11	GND	-			M11	GND	-		
M12	GND	-			M12	GND	-		
M13	GND	-			M13	GND	-		
M14	GND	-			M14	GND	-		
M15	GND	-			M15	GND	-		
M16	GND	-			M16	GND	-		
M17	GND	-			M17	GND	-		
N10	GND	-			N10	GND	-		
N11	GND	-			N11	GND	-		
N12	GND	-			N12	GND	-		
N13	GND	-			N13	GND	-		
N14	GND	-			N14	GND	-		
N15	GND	-			N15	GND	-		
N16	GND	-			N16	GND	-		
N17	GND	-			N17	GND	-		
P10	GND	-			P10	GND	-		
P11	GND	-			P11	GND	-		
P12	GND	-			P12	GND	-		
P13	GND	-			P13	GND	-		
P14	GND	-			P14	GND	-		
P15	GND	-			P15	GND	-		
P16	GND	-			P16	GND	-		
P17	GND	-			P17	GND	-		
R10	GND	-			R10	GND	-		
R11	GND	-			R11	GND	-		
R12	GND	-			R12	GND	-		
R13	GND	-			R13	GND	-		
R14	GND	-			R14	GND	-		
R15	GND	-			R15	GND	-		
R16	GND	-			R16	GND	-		
R17	GND	-			R17	GND	-		
T10	GND	-			T10	GND	-		
T11	GND	-			T11	GND	-		
T12	GND	-			T12	GND	-		
T13	GND	-			T13	GND	-		
T14	GND	-			T14	GND	-		
T15	GND	-			T15	GND	-		
T16	GND	-			T16	GND	-		
T17	GND	-			T17	GND	-		
U10	GND	-			U10	GND	-		
U11	GND	-			U11	GND	-		

Date	Version	Section	Change Summary
December 2004	01.4	Architecture	Updated Hot Socketing Recommended Power Up Sequence section.
		Pinout Information	Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Pin Information
			Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Power Supply and NC Connections
			Added LFEC1 and LFEC3 100 TQFP Pinout
			Added LFEC1 and LFEC3 144 TQFP Pinout
			Added LFEC1, LFEC3 and LFECP/EC10 208 PQFP Pinout
			Added LFEC3, LFECP/EC10 and LFECP/EC15 256 fpBGA Pinout
			Added LFECP/EC10 and LFECP/EC15 484 fpBGA Pinout
		Ordering Information	Added Lead-Free Package Designators
			Added Lead-Free Ordering Part Numbers
		Supplemental Information	Updated list of technical notes.
April 2005	01.5	Architecture	EBR memory support section has been updated with clarification.
			Updated sysIO buffer pair section.
		DC & Switching Characteristics	Hot Socketing Specification has been updated.
			DC Electrical Characteristics table (I_{IL}, I_{IH}) has been updated.
			Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			External Switching Characteristics section has been updated.
			Removed t_{RSTW} spec. from PLL Parameter table.
			t_{RST} specifications have been updated.
			sysCONFIG Port Timing Specifications (t_{BSCL}, t_{IODISS}, t_{PRGMRJ}) have been updated.
		Pinout Information	Added LFECP/EC33 Pinout Information
			Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
			484-fpBGA logic connection has been updated (Ball # J6, J17, P6 and P17 for ECP/EC33 are now called VCCPLL).
			672-fpBGA logic connection has been updated (Ball # K19, L8, U19, U8 for ECP/EC33 are now called VCCPLL).
May 2005	01.6	Introduction	ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.
		Architecture	Table 2-10 has been updated (ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.)
			Recommended Power Up Sequence section has been removed.
		DC & Switching Characteristics	Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			Vos test condition has been updated to (VOP+VOM)/2.
			Register-to-Register performance table has been updated (rev. G 0.27).
			External switching characteristics have been updated (rev. G 0.27).
			Internal timing parameters have been updated (rev. G 0.27).
			Timing adders have been updated (rev. G 0.27).
			sysCONFIG port timing specifications have been updated.
		Pinout Information	Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	OPN list has been updated.

Date	Version	Section	Change Summary
September 2005	02.0	Architecture	sysIO section has been updated.
		DC & Switching Characteristics	Recommended Operating Conditions has been updated with V_{CCPLL}.
			DC Electrical Characteristics table has been updated
			Removed 5V Tolerant Input Buffer section.
			Register-to-Register performance table has been updated (rev. G 0.28).
			LatticeECP/EC External Switching Characteristics table has been updated (rev. G 0.28).
			LatticeECP/EC Internal Switching Characteristics table has been updated (rev. G 0.28).
			LatticeECP/EC Family Timing Adders have been updated (rev. G 0.28).
			sysCLOCK PLL timing table has been updated (rev. G 0.28)
			LatticeECP/EC sysCONFIG Port Timing specification table has been updated (rev. G 0.28).
			Master Clock table has been updated (rev. G 0.28).
			JTAG Port Timing specification table has been updated (rev. G 0.28).
		Pinout Information	Signal Description table has been updated with V_{CCPLL}.
November 2005	02.1	DC & Switching Characteristics	Pin-to-Pin Performance table has been updated (G 0.30) - 4:1MUX, 8:1MUX, 16:1MUX, 32:1MUX Register-to-Register Performance (G 0.30) - No timing number changes.
			External Switching Characteristics (G 0.30) - No timing number changes.
			Internal Switching Characteristics (G 0.30) -t_{SUP_DSP}, t_{HP_DSP}, t_{SUO_DSP}, t_{HO_DSP}, t_{COI_DSP}, t_{COD_DSP} numbers have been updated.
			Family Timing Adders (G 0.30) - No timing number changes.
			sysCLOCK PLL Timing (G 0.30) - No timing number changes.
			sysCONFIG Port Timing Specifications (G 0.30) - No timing number changes.
			Master Clock (G 0.30) - No timing number changes.
			JTAG Port Timing Specification (G 0.30) - No timing number changes.
		Ordering Information	Added 208-PQFP lead-free part numbers.
March 2006	02.2	DC & Switching Characteristics	Added footnote 3. to V_{CCAUX} in the Recommended Operating Conditions table.
January 2007	02.3	Architecture	EBR Asynchronous Reset section added.
February 2007	02.4	Architecture	Updated EBR Asynchronous Reset section.
			Updated Maximum Number of Elements in a Block table - MAC value for x9 changed to 2.
May 2007	02.5	Architecture	Updated text in Ripple Mode section.
November 2007	02.6	DC & Switching Characteristics	Added JTAG Port Waveforms diagram.
			Updated t_{RST} timing information in the sysCLOCK PLL Timing table.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
February 2008	02.7	DC & Switching Characteristics	Read/Write Mode (Normal) and Read/Write Mode with Input and Output Registers waveforms in the EBR Memory Timing Diagrams section have been updated.
September 2012	02.8	All	Updated document with new corporate logo.